

CLAIMS

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1. A flow sensor comprising  
a housing with at least two housing sections and forming a measuring conduit between at least some of said housing sections,  
a semiconductor chip comprising a sensor element arranged at a wall of the measuring conduit,  
a sealing ring arranged between two of said housing sections and surrounding said semiconductor chip, said sealing ring pressing against a support formed by at least one of said housing sections, and  
at least one strip conductor connected to the semiconductor chip and extending between said support and said sealing ring and out of said housing.
2. The flow sensor of claim 1 wherein said sealing ring is pressed against said strip conductor.
3. The flow sensor of claim 1 wherein said strip conductor is arranged on one of said housing sections.
4. The flow sensor of claim 3 further comprising a printed circuit board forming at least part of one of said housing sections, wherein said strip conductor is arranged on said printed circuit board.
5. The flow sensor of claim 4 wherein the printed circuit board is arranged between the sealing ring and the support.
6. The flow sensor of claim 1 further comprising a flexible support foil wherein said strip conductor is arranged on said support foil.
7. The flow sensor of claim 1 wherein said measuring conduit is formed by a groove in a surface of at least one of the housing sections, wherein said sealing ring sur-

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rounds said groove, said flow sensor comprising at least two connecting ducts extending through at least one of said housing sections and communicating with said measuring duct.

8. The flow sensor of claim 7 wherein said sealing ring is arranged at said surface.

9. The flow sensor of claim 7 wherein said sealing ring is arranged in a recess in said surface.

10. The flow sensor of claim 1 wherein said measuring conduit is formed by a groove in a surface of a first housing section,

and wherein said semiconductor chip is arranged in a recess in a surface of a second housing section, is flush with a wall of the measuring conduit, and contacts said first housing section.

11. The flow sensor of claim 10 further comprising at least one spacer between said semiconductor chip and a bottom of said recess, said spacer being deformed by a force exerted by said first housing section on said semiconductor chip.

12. The flow sensor of claim 11 wherein said spacer comprises a plurality of bumps located in said bottom of said recess and comprising tips, said tips being deformed by said force.

13. The flow sensor of claim 12 wherein said bumps are an integral part of said second housing section.

14. The flow sensor of claim 10 wherein said recess comprises a side wall parallel to said measuring conduit, said side wall ending in recessed sections, such that said side wall forms a straight stop for positioning the semiconductor chip in a direction perpendicular to said measuring conduit.

**SECRET**

17. The flow sensor of claim 1 wherein said semiconductor chip is arranged closer to an exit end than to an entry end of the measuring conduit.